

PVD 200™

Open Frame, Load Lock PRO Line Thin Film Deposition System



Kurt J. Lesker
Company

PROCESS EQUIPMENT™
DIVISION

Applications

- Designed for university, industrial, and government lab R&D thin film deposition
- OLED/PLED and organic electronics applications
- Photovoltaics and semiconductor devices
- Optics and decorative coatings
- Small batch production

Features

- Enclosed instrument rack and chamber base
- 304L stainless steel box chamber with aluminum door and large viewport
- Manual touch-screen or recipe-controlled, PC based process automation
- Turbomolecular or optional cryogenic high vacuum pumping

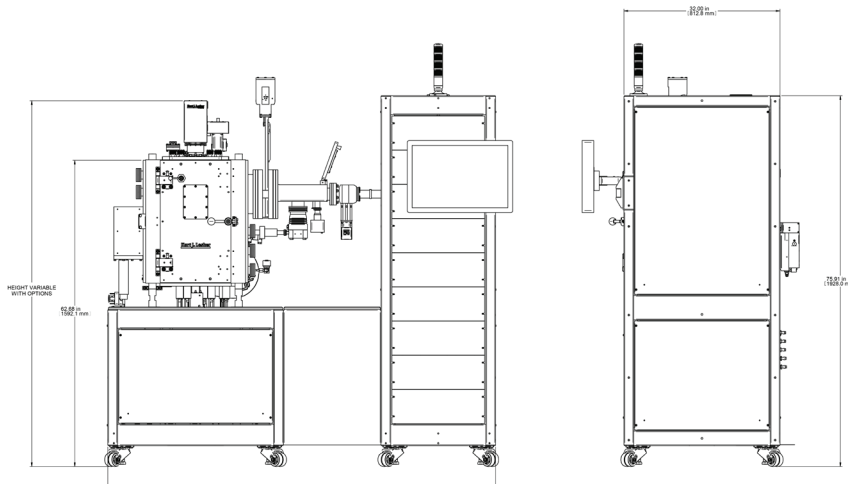
Process Modules

- Magnetron sputtering: RF, DC, Pulsed DC, High-power pulsed magnetron sputtering (HiPIMS/HPPMS)
- Electron beam evaporation
- Thermal evaporation
- Organic materials evaporation
- Ion source substrate cleaning or assisted deposition

Options

- Substrate heating, cooling, or biasing
- Planetary substrate fixturing
- Upstream or downstream pressure control
- Film thickness control
- Substrate load lock
- On-site installation and training

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Specifications

Dimensions Approximate

Process Chamber Volume	19.25" wide x 20.5" deep x 24" high (488.95mm Wide x 520.7mm Deep x 609.6mm High) Ideal for sputtering applications or shorter throw evaporation or e-beam	155 liters
	19.25" wide x 20.5" deep x 36" high (488.95mm Wide x 520.7mm Deep x 914.4mm High) Ideal for long throw evaporation or e-beam	232 liters
	Aluminum, O-ring sealed, hinged, front access door O-ring sealed side plates (2), allow for maximum modularity and upgradeability	
Process Chamber Construction	304L Stainless Steel with 6061 Aluminum Hinged Door	
Cabinet Construction	Carbon Steel, Fully Enclosed Instrument Rack, Open Chamber Area, Gray Powder Coat Finish	
Deposition Sources (Available in various combinations)	Up to (8) 2' or 3" Torus® Magnetron Sputtering Cathodes	
	4-Pocket 8cc Electron Beam Source, 8-Pocket 12cc, and 6-Pocket 20cc Available	
	Up to (6) 4" Thermal Evaporation Sources	
	Up to (2) LTE Organic Material Evaporation Sources	
Deposition Orientation	Sputter Up, Evaporation Up	
Substrate Cleaning	Ion Source or Bias eH400 end-Hall ion Source, KDC40 gridded ion source, or 100W RF Bias	
Substrate Size (max)	Single 8" (200mm) with 20 RPM Max Variable Rotation	
Substrate Heating/Cooling	Up to 850°C or water cooled	
Standard Vacuum Pumping Base Pressure (CDE)	790 l/sec Turbo Pump — 9 x 10 ⁻⁷ torr (1.2 x 10 ⁻⁶ mbar) 1250 l/sec Turbo — 5 x 10 ⁻⁷ torr (6.7 x 10 ⁻⁷ mbar) 1500 l/sec Cryo Pump Available — 8 x 10 ⁻⁸ torr (1.1 x 10 ⁻⁷ mbar) 3000 l/sec Cryo Pump Available — 5 x 10 ⁻⁸ torr (6.7 x 10 ⁻⁸ mbar)	
Process Gas	4 Channel Mass Flow Control with 3-position or variable position gate valve	
System Control	PC-Based HMI, eKlipse™ advanced recipe control and datalogging	
Required Power (typical, based on options)	208VAC, 3Ø, 50/60 Hz; Optional 380VAC, 3Ø, 50/60 Hz	
Available Certifications, Markings	Systems within the European Economic Area (EEA) are CE marked and comply with the following EU directives: -Low Voltage Directive (LVD) 2014/35/EU -Electromagnetic Compatibility (EMC) Directive 2014/30/EU Systems outside of the EEA can be CE marked as required CSA and NRTL certification is available	
Warranty	12 Months upon Shipment	
Overall Dimensions (approx)	79.5" (2019.3mm) wide x 32" (812.8mm) deep x 75.9" (1928mm) high	
Weight (approx)	2,200 lbs (998 kg)	

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